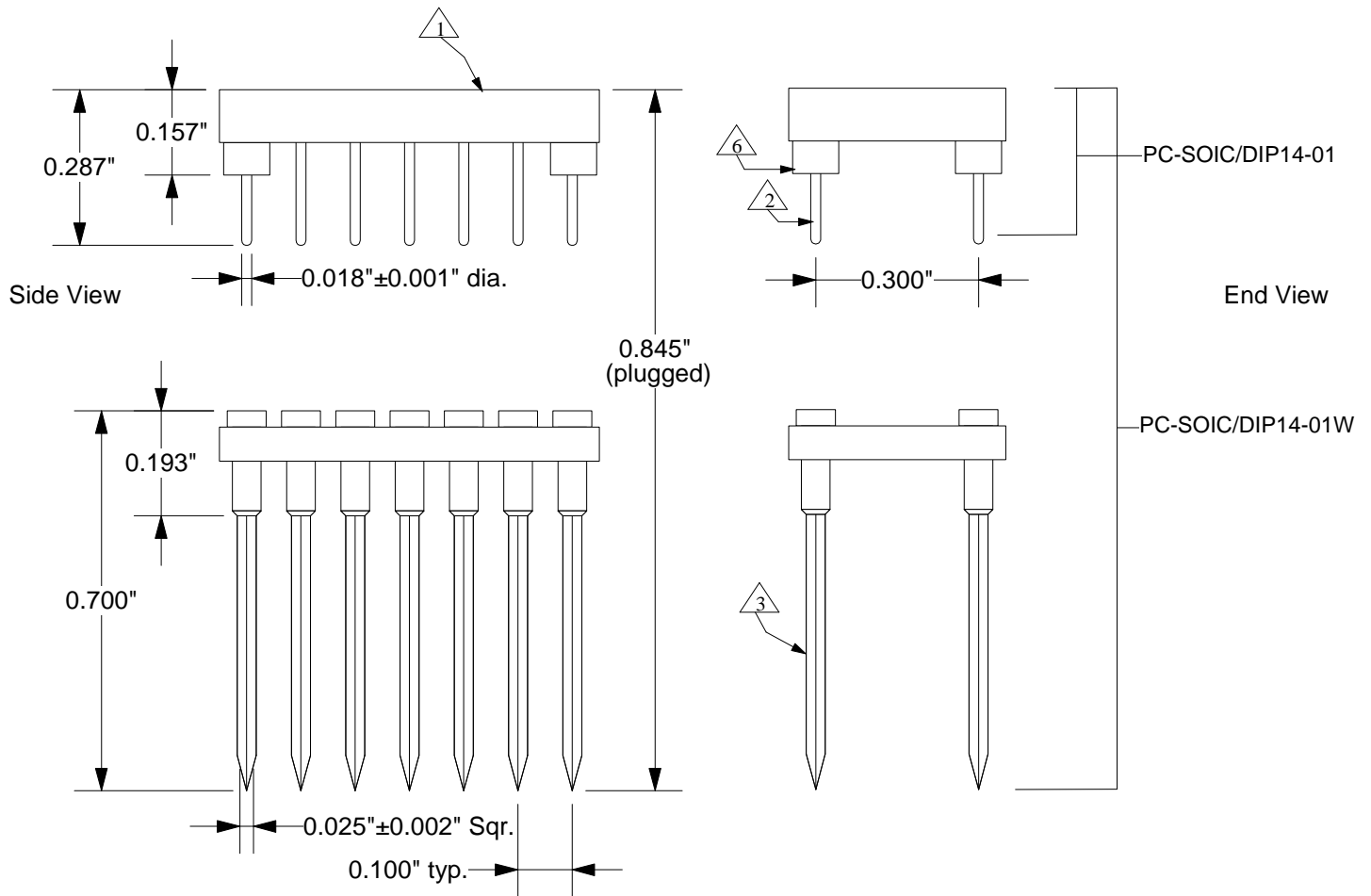


- △1 Substrate: 0.097"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- △2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- △3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)
- △6 Stand-off: material- Teflon; 0.090" Dia; 0.060" thick.

Top View




Description: PACKAGE CONVERTOR

14 position (0.05" pitch) SOIC SM land pattern to 0.3" wide dip, round machined pins. Pin assignment; 1:1. Add "W" to part # for optional wire wrap sub base.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

Old part # PC-SOR/DIP14-01

	PC-SOIC/DIP14-01 (w) Drawing	Status: released	Scale: 3:1	Rev: A
	© 1998 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing by: P LeBeau		Date: 2/17/98
		File: PC-SOIC/DIP14-01 Dwg	Modified:	